



(0,80 mm) .0315"

HSEC8-130-01-S-D-EM2

HSEC8-140-01-L-D-EM2

HSEC8-EM SERIES

EDGE MOUNT EDGE RATE® CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-EM

Insulator Material:

Liquid Crystal Polymer

Contact:

BeCu

Plating:

Au or Sn over
50µ" (1,27 µm) Ni

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3,15 mm) .125" nominal

Lead-Free Solderable:

Yes

RoHS Compliant:

Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

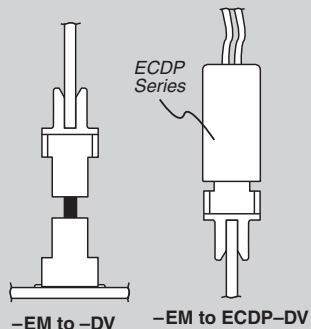


FILE NO. E111594

Mates with:

(1,60 mm) .062" thick cards,
ECDP, HSC8

APPLICATIONS



Mates with
(1,60 mm) .062" cards

Solder Tab
for added
strength

Terminates to
(1,60 mm) .062"
board

HSEC8

1

POSITIONS
PER ROW

01

PLATING
OPTION

D

EM2

10, 20, 30, 40, 50, 60

-L

= 10µ" (0,25 µm) Gold on contact,
Matte Tin on tail

-S

= 30µ" (0,76 µm) Gold on contact,
Matte Tin on tail

-EM2

= (1,60 mm) .062"
thick PCB

ALSO AVAILABLE (MOQ Required)

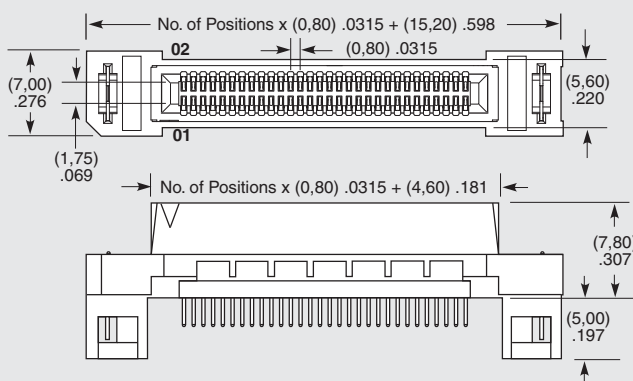
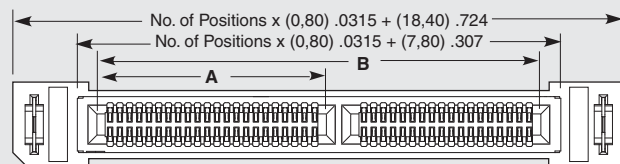
- Other platings
Contact Samtec.

OTHER SOLUTIONS

Polarized mates for
ECDP Series twinax cables

| CONNECTOR | CABLE |
|-----------|---------|
| HSEC8-113 | ECDP-08 |
| HSEC8-125 | ECDP-16 |
| HSEC8-137 | ECDP-24 |
| HSEC8-149 | ECDP-32 |

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.



| POSITIONS PER ROW | A | B |
|----------------------|------------------|------------------|
| 40 | (18,90) .744 | (36,60) 1.441 |
| 50 | (22,90) .902 | (44,60) 1.756 |
| 60 | (26,90) 1.059 | (52,60) 2.071 |